

TABLE OF DIMENSIONS										
BURNDY CATALOG NO.	CONTACTS PER ROW	TOTAL NO CONTACTS	NUMBER OF CONTACT PAIRS			D	E	F	G±.008 [0,20]	J
			BAY A	BAY B	BAY C					
CEE2X97S-V_Z14	97	194	42	45	10	2.140 [54,36]	2.288 [58,12]	2.890 [73,41]	5.290 [134,37]	0.180 [4,57]
CEE2X101S-V_Z14	101	202	42	49	10	2.140 [54,36]	2.488 [63,20]	3.090 [78,49]	5.490 [139,45]	0.180 [4,57]
CEE2X91S-V_Z14	91	182	42	49	---	2.140 [54,36]	2.490 [63,25]	---	4.890 [124,21]	0.180 [4,57]
CEE2X101S-V_Z34	101	202	42	49	10	2.140 [54,36]	2.488 [63,20]	3.090 [78,49]	5.490 [139,45]	0.150 [3,81]

CATALOG NO. DESCRIPTION

CE E 2X 97 S - V 12

CONNECTOR SERIES
EDGE CARD

CONTACT SPACING
E=.050 [1,27] PITCH

NUMBER OF ROWS

NUMBER OF CONTACTS
PER ROW: 91, 97, 101

PLATING DESIGNATION

DESIGN VARIATIONS

11- .100±.010 [2,54±0,25] TAIL LENGTH, TRI-POSTS
WITH ALTERNATE POSITION NO. 1.

12- .100±.010 [2,54±0,25] TAIL LENGTH, TRI-POSTS

28- .140±.010 [3,56±0,25] TAIL LENGTH, TRI-POSTS

42- .100±.010 [2,54±0,25] TAIL LENGTH, TRI-POSTS

.150 [3,81] LONG (CEE2X101 ONLY)

V-GROOVE STABILIZER CARD SLOT

TERMINATION STYLE
S= SOLDER TAIL

NOTES: UNLESS OTHERWISE SPECIFIED;

- INTERPRET THIS DRAWING IN ACCORDANCE WITH ANSI Y14.5M - 1982.
- SEE SHEETS 3 AND 4 FOR RECOMMENDED MATING P.C. BOARD CONTACT PAD AND BACKPLANE LAYOUTS.

MATING P.C. BOARD MATERIAL:
P.C. BOARD: FR-4 WITH 1 oz. [28,35 GRAMS] MIN COPPER PADS

PAD PLATING: 30 MICROINCHES [0,76 MICRONS] MIN. GOLD PER MIL-G-45204 TYPE 1, CLASS 1, GRADE C, OVER 100 MICROINCHES [2,54 MICRONS] MIN. NICKEL PER QQ-N-290.

MATERIALS:

BODY: GLASS-FILLED THERMOPLASTIC, RATED UL94V-0
COLOR- NATURAL

CONTACTS: COPPER ALLOY

CONTACT FINISH:

Z14 PLATING: GOLD FLASH OVER 40 MICROINCHES [1,02 MICRONS] MIN.
PALLADIUM-NICKEL OVER 50 MICROINCHES [1,27 MICRONS] MIN. NICKEL UNDERPLATE IN CRITICAL CONTACT AREA AND 100 MICROINCHES [2,54 MICRONS] SOLDER OVER NICKEL UNDERPLATE ON SOLDER TAILS.

Z34 PLATING: 15 MICROINCHES [0,38 MICRONS] MIN. GOLD OVER 50 MICROINCHES [1,27 MICRONS] MIN. NICKEL UNDERPLATE IN CRITICAL CONTACT AREA AND 100 MICROINCHES [2,54 MICRONS] SOLDER OVER NICKEL UNDERPLATE ON SOLDER TAILS.

PERFORMANCE CHARACTERISTICS:

CONTACT RESISTANCE
(LOW SIGNAL LEVEL): MIL-STD-1344, METHOD 3002-1, 30 MILLIOHMS
MAXIMUM INITIAL, 10 MILLIOHMS MAXIMUM INCREASE THROUGH TESTING.

CURRENT RATING: 1 AMP. PER EACH POWER CONTACT.

CONTACT NORMAL FORCE: 1.76 OZ FORCE [0,49 NEWTONS] MIN END OF LIFE.

DURABILITY: 100 MATING CYCLES WITHOUT PHYSICAL DAMAGE
OR EXCEEDING LOW LEVEL CONTACT RESISTANCE
REQUIREMENT WHEN MATED WITH RECOMMENDED CARD EDGE.

INSULATION RESISTANCE: MIL-STD-202, METHOD 302, CONDITION B,
1000 MEGAOHMS MINIMUM

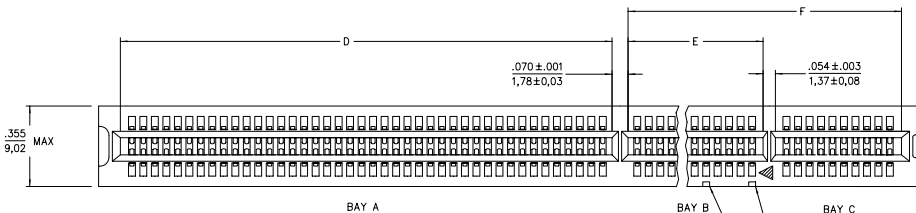
OPERATING TEMPERATURE: -40°F TO 221°F [-40°C TO 105°C]

THERMAL SHOCK: MIL-STD-1344, METHOD 1003.1
-67°F TO 185°F [-55°C TO 85°C], 5 CYCLES.

CAPACITANCE: 2 PICOFARADS, MAXIMUM AT 1 MEGAHERTZ.

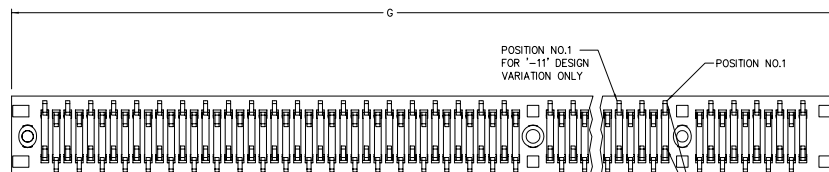
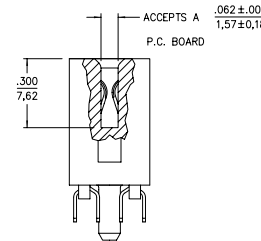
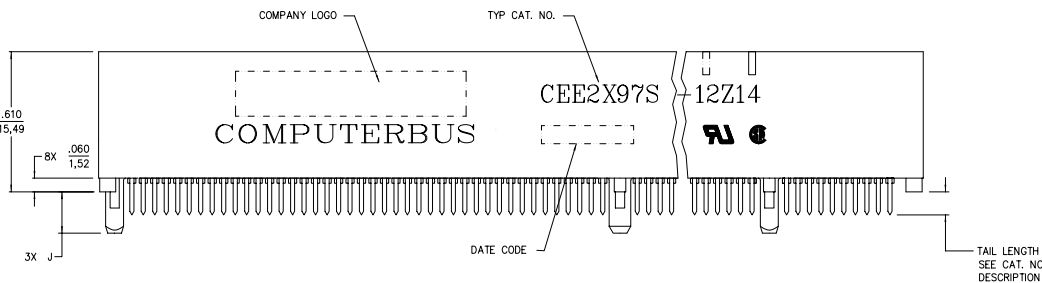
BOTH CONTACTS AND BODY ARE ABLE TO WITHSTAND VAPOR PHASE
TEMPERATURE EXPOSURE.

MATING FORCE: MIL-STD-1344, METHOD 2013.1, 6 OZ FORCE [1,668 NEWTONS]
MAXIMUM AVERAGE PER OPPOSING PAIR USING GAUGE
PER MIL-STD-C-21097. EXCEPT .062[1,57] THICK,
WITH 20° ANGLE.



ALTERNATE POSITION NO.1
INDICATOR, FOR '-11'
DESIGN VARIATION ONLY

POSITION NO.1 INDICATOR
(REFERENCE ONLY)



CEE2X97S-12Z14 SHOWN

mat'l. code				surface		tolerance	projection	product family	
				ISO 1302 ✓		ISO 406 ISO 1101		CARDEGE	
ltr	ecn	no	dr	date	tolerances unless otherwise specified			title	
B	V90772	CKW	04/14/99		angles	linear	.X±.1/2.5	COMPUTERBUS CARD EDGE	
C	V01851	CKW	07/24/00				.XX±.02/0.5	CONNECTOR	
D	V02096	CKW	09/07/00	0'±1'			.XXX±.005/0.13	scale 4:1	
E	M06-0234	AGS	06/16/06	dr	YIP		04/01/92	dwg no	
				enr	BM		04/02/92	sheet 1 of 4	
				chr	JB		04/20/92	SE94876	
				appd				A3	
sheet	revision	E	E	E	E	E		type Product Customer Drawing	
index	sheet	1	2	3	4				

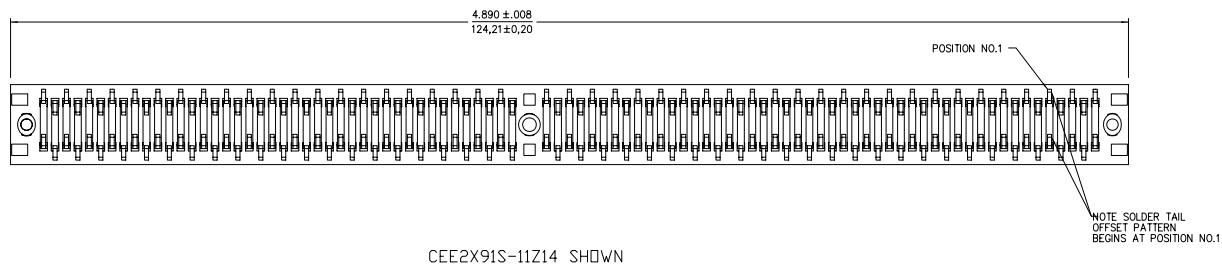
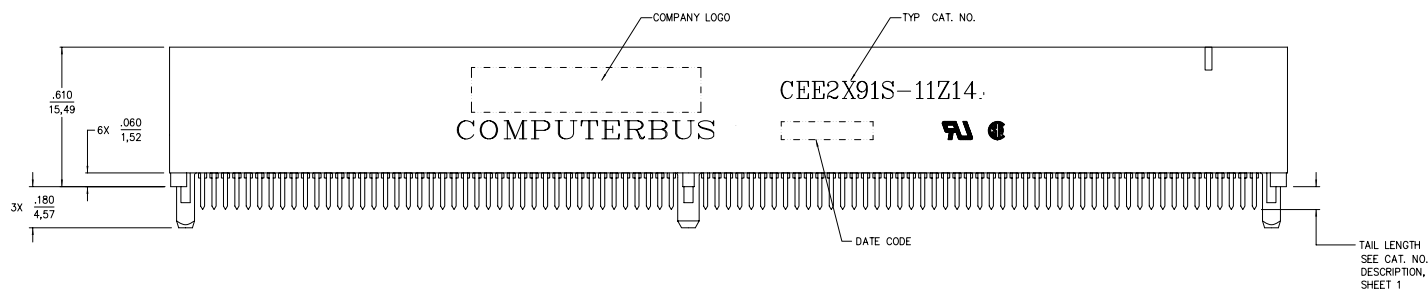
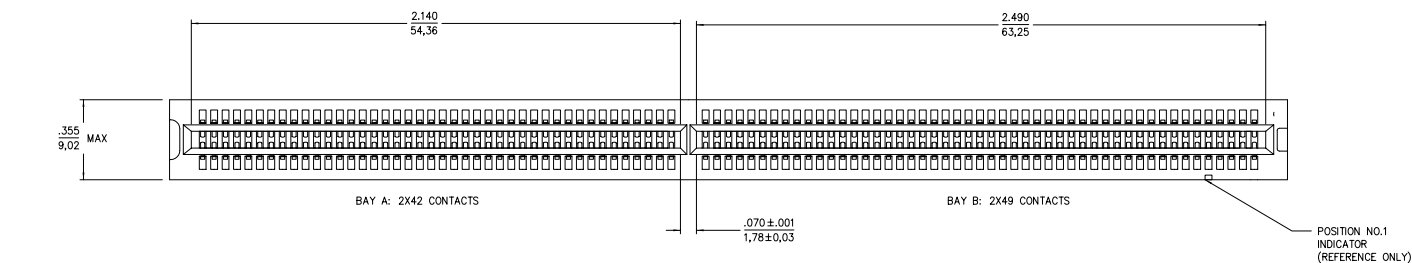
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NOTES: SEE SHEET 1.



CEE2X91S-11Z14 SHOWN

mat'l. code					surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection 		product family CARDEDGE				
ltr ecn no dr date					tolerances unless otherwise specified							title			
E					angles		linear		INCH/MM		COMPUTERBUS CARD EDGE CONNECTOR				
							.X±.1/2.5								
							.XX±.02/0.5								
					0°±1'		.XXX±.005/0.13		scale 4:1						
					dr		YIP		04/01/92		dwg no sheet2 of 4 siz				
					enrg		BM		04/02/92		SE94876 A				
					chr		JB		04/20/92						
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sheet index		revision sheet													

form: A3

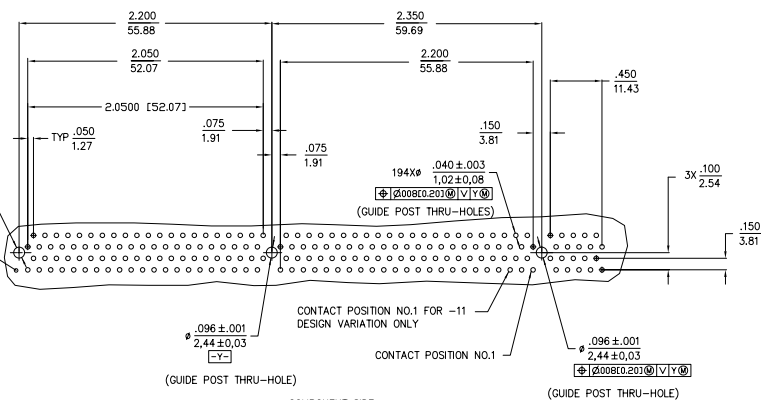


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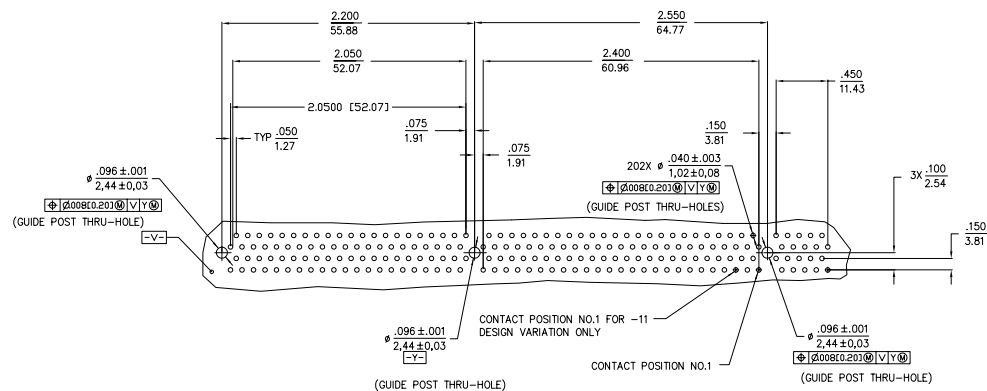


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CD



BACKPLANE LAYOUT FOR CEE2X97S-__Z14
CONNECTOR SOLDER TAILS AND GUIDE POSTS



BACKPLANE LAYOUT FOR CEE2X101S-__Z__
CONNECTOR SOLDER TAILS AND GUIDE POSTS

PDM: Rev:E STATUS: **Released** Printed: Dec 01, 2009